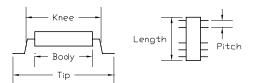
PA20-08-5-2808-3(6) Data Sheet 20 Pin SO socket/8 Pin DIP 0.3" or 0.6" plug

Supported Device/Footprints

Using this adapter, several Xilinx EEPROM's in their 20 pin SO package can be programmed in their 8 pin DIP footprint. This adapter is general purpose, and is known to work for the following devices:

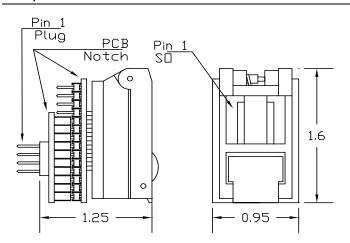
	Device		Footprint		
Mfgr	Device	Package	Device	Package	
Xilinx	XC1701(L)(P)	SO	XC1701(L)(P)	DIP	
"	XC17512L	"	XC17512L	"	

The SO socket accepts packages with the dimensions listed below:



Body mm (inches)			Knee mm (inches)		
min.	typ.	max.	min.	typ.	max.
7.4	7.8	7.9	n/a	9.3	9.4
(0.291)	(0.307)	(0.311)		(0.366)	(0.370)
Tip mm (inches)					
•	(inches)		Body I	Length	Lead Pitch
Tip mm min.	(inches)	max.	Body I	Length	

Adapter Dimensions



Adapter Construction

The adapter is made up of 3 sub-assemblies. They assemble via connectors making the adapter modular. This way the sub-assemblies can be replaced when they wear out.

When disassembling the adapter take care not to bend the pins. When reassembling the adapter note the pin 1 indicators to align the parts correctly.

Test Socket

SO Lidded test socket:

Enplas Part #: FP-20(28)-1.27-08 LSC Part #: 20(28H)SD-08

28SO08

Accepts the test socket and connects to the bottom board.

20-08-5-(3 or 6)

Performs the wiring shown in the Adapter Wiring section

Adapter Wiring

The following chart shows the connections from the SO device to the adapter's DIP plug.

DEVICE	SIGNAL	PLUG
1	DATA	1
2	NC	-
3	CLK	2
4	NC	-
5	NC	-
6	NC	-
7	NC	-
8	RESET/OE*	3
9	NC	-
10	CE*	4
11	GND	5
12	NC	-
13	CEO*	6
14	NC	-
15	NC	-
16	NC	-
17	NC	-
18	VPP	7
19	NC	-
20	VCC	8